











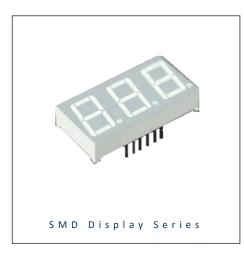




- ► PTH Display
- ▶ 0.56" (14.2mm) 8.8.8.
- ► Green (570nm)

NOG14D94GS N0G14D95GS





# PTH Display Series Compliant





#### **FEATURES:**

- Package: PTH Numeral Triple Digits Display
- Forward Current: 20mA per diode
- Forward Voltage (typ.): 2.1V per diode
- Luminous Intensity (typ.): 2.3mcd @20mA per diode
- Colour: Green
- Wavelength: 570nm
- Materials:
  - Die: AlInGaP
  - Resin: Epoxy (White Diffused)
  - Surface Colour: Grey
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping parameters:** 
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- Soldering methods: Reflow
- Preconditioning: acc. to JEDEC Level 3
- Packing: 400pcs/carton

### **APPLICATIONS:**

- 7-Segment Display
- **Triple Digital Display**
- Information Board
- White Goods
- Counter



### **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current *	l <sub>F</sub>	25	mA
Peak Forward Current Duty 1/10 @1KHz	I <sub>FP</sub>	100	mA
Reverse Current @5V	I <sub>R</sub>	10	μΑ
Power Dissipation	P <sub>D</sub>	85	mW
Operating Temperature	TOPR	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

<sup>1.</sup> All parameters are per diode.

# Electrical & Optical Characteristics (Ta=25°C)

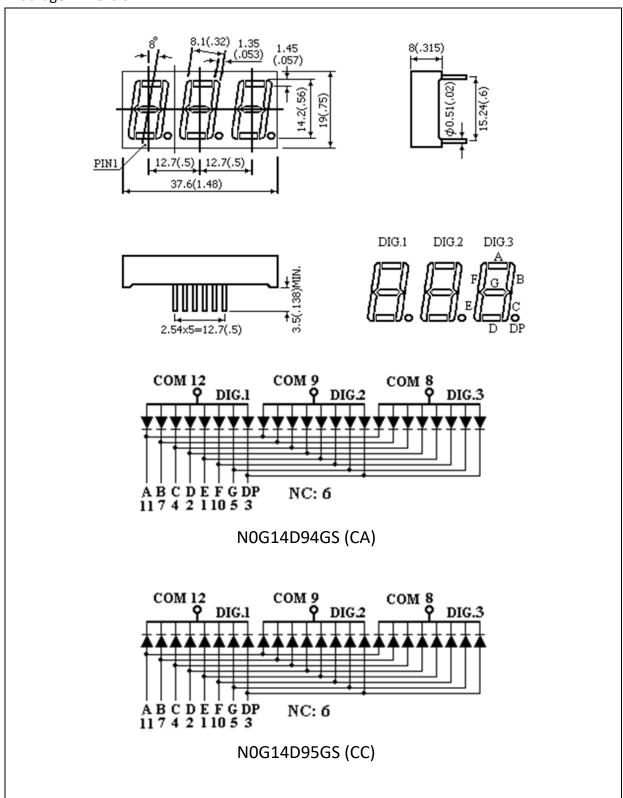
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Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	1.7	2.1	2.6	V	I <sub>F</sub> =20mA
Luminous Intensity	l <sub>V</sub>	1.1	2.3	3.5	mcd	I <sub>F</sub> =20mA
Peak Wavelength	$\lambda_{P}$		568		nm	I <sub>F</sub> =20mA
Dominant Wavelength	$\lambda_{D}$		570		nm	I <sub>F</sub> =20mA
Spectral Line Half Bandwidth	Δλ		30		nm	I <sub>F</sub> =20mA

<sup>1.</sup> Luminous intensity (I<sub>V</sub>)  $\pm 15\%$ , Forward Voltage (V<sub>F</sub>)  $\pm 0.1$ V, Viewing angle( $2\theta_{1/2}$ )  $\pm 5\%$ 



#### **OUTLINE DIMENSION:**

### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



# **BINNING GROUPS:**

# Forward Voltage Classifications (I<sub>F</sub> = 20mA):

Code	Min.	Max.	Unit
V	1.7	2.6	V

# Luminous Intensity Classifications (I<sub>F</sub> = 20mA):

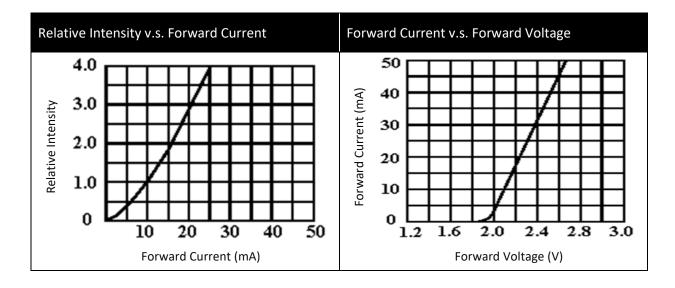
Code	Min.	Max.	Unit
IV	1.1	3.5	mcd

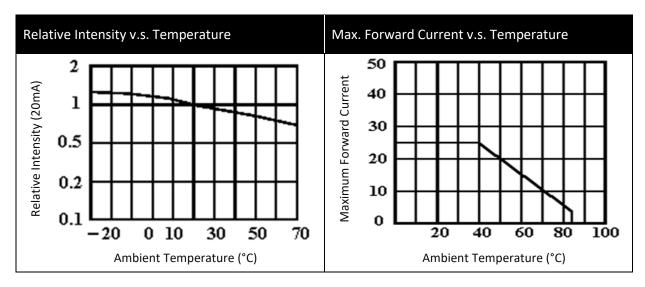
# Dominant Wavelength Classifications (I<sub>F</sub> = 20mA):

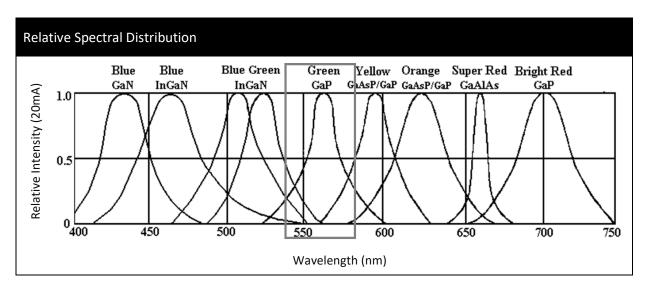
Code	Min.	Max.	Unit
G	565	575	nm



#### **ELECTRO-OPTICAL CHARACTERISTICS:**







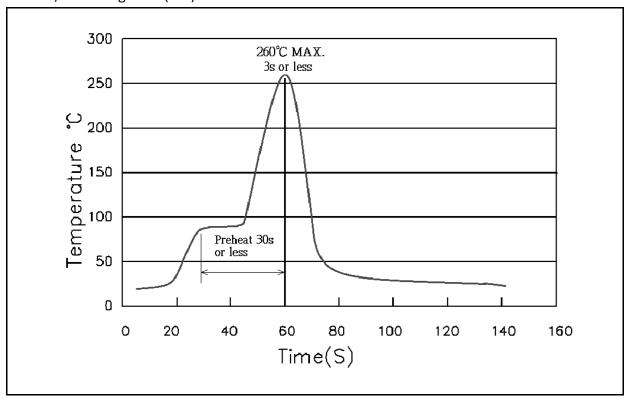


#### **RECOMMENDED SOLDERING PROFILE:**

### Hand Solder (Solder Iron):

- Temperature at tip of iron: 300°C Max. (25W Max.).
- Soldering Time: 3 seconds ± 1 sec.
- Maximum reflow soldering: 1 time.

### Wave / Soldering Heat (DIP):

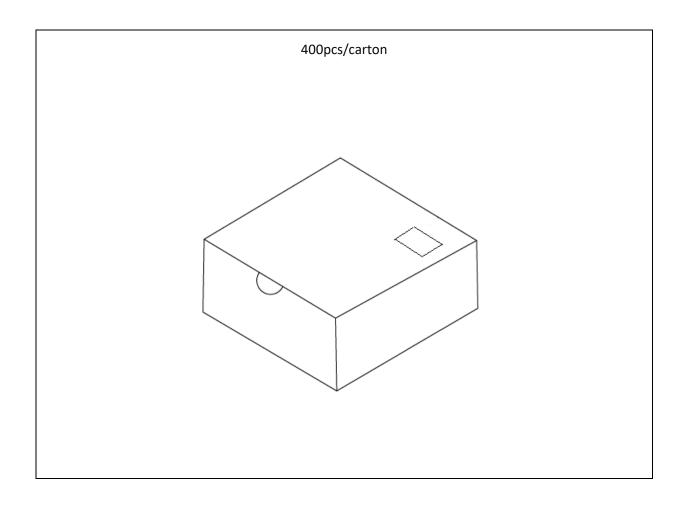


#### Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



# **PACKING SPECIFICATION:**





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking.

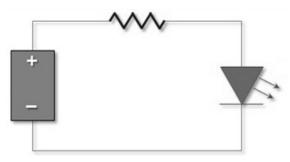
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	24/11/2014	Datasheet set-up.
A1.1	14/08/2019	Datasheet update.